

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Robert A. Boudreau  
Songsheng Tan

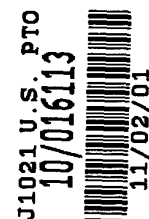
Examiner:

Serial No:

Group Art Unit:

Filed:

For: SILICON WAFERBOARD



INFORMATION DISCLOSURE STATEMENT  
UNDER 37 C.F.R. §§ 1.56, 1.97 - 1.98

Asst. Commissioner of Patents and Trademarks  
Washington, DC 20231

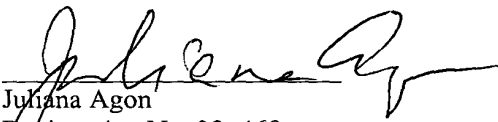
Dear Sir:

The Examiner's attention is hereby directed to the following reference(s) listed on the attached Form PTO-1449 for consideration in connection with the examination of the above-identified patent application. One copy of the reference(s) is enclosed.

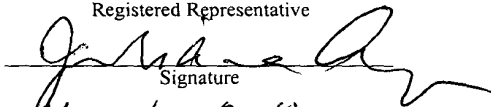
This submission does not represent that a search has been made or that no better art exists and does not constitute an admission that each or all of the enclosed documents constitute "prior art." If it should be determined that any of the submitted documents do not constitute "prior art" under United States law, applicant(s) reserve the right to present to the office the relevant facts and law regarding the appropriate status of such documents.

Applicant(s) further reserve the right to take appropriate action to establish the patentability of the disclosed invention over the enclosed references, should one or more of the references be applied against the claims of the present application.

Respectfully submitted,

  
Juliana Agon  
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Corning Incorporated  
SP-TI-03-1  
Corning, NY 14831  
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Date: November 2, 2001

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Asst. Commissioner of Patents and Trademarks, Washington, D.C. 20231	
on <u>November 2, 2001</u>	Date of Deposit
Juliana Agon Name of applicant, assignee, or Registered Representative	
 Signature	
<u>November 2, 2001</u> Date of Signature	

FORM PTO-1449 (MODIFIED)  LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT	ATTORNEY DOCKET NO.	SERIAL NO.
	SP01-319	
	APPLICANT Boudreau et al.	
	FILING DATE	GROUP:

J1D21 U.S. PTO  
 10/016113  
 11/02/01

REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA	6,195,495B1	2/2/01	Ota, et al	385	137	
	AB	5,778,123	7/7/98	Hagan, et al	385	76	
	AC	5,940,562	8/17/99	Henson, et al	385	88	
	AD	5,343,544	8/30/94	Boyd, et al	385	46	
	AE	5,311,604	5/10/94	Rogner, et al	385	14	
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
	AL	WO96/21875	7/18/96	PCT			
	AM						
	AN						
	AO						
	AP						
	AQ						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)	
AR	"Hybrid optoelectronic integration of transmitter arrays on silicon waferboard" Armiento, et al Optoelectronics for Communication and Processing 112, SPIE Vol. 1582
AS	"A Surface Mount Single-Mode Laser Module Using Passive Alignment" Kurata, et al IEEE Transactions on Components, Packaging, and Manufacturing Technology Prt B, Vol. 19, No. 3, August 1996
AT	
AU	
AV	
AW	

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

(U.S.)

Attorney Docket No.: SP01-319

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicant(s):** Boudreau, et al

**Serial No.:**

**Filed:**

**For:** SILICON WAFERBOARD

**COMBINED  
CERTIFICATE UNDER  
37 C.F.R. § 3.73(b)  
and  
POWER OF ATTORNEY**

Assistant Commissioner for Patents  
Washington, DC 20231

**CERTIFICATE UNDER 37 C.F.R. § 3.73(b)**

**CORNING INCORPORATED**, a New York corporation, certifies that it is the assignee of the entire right, title and interest in the patent application identified above by virtue of an assignment from the inventor(s) of the patent application identified above. A true copy of the unrecorded Assignment is attached hereto.

The undersigned has reviewed the above referenced assignment of the patent application identified above and, to the best of the undersigned's knowledge and belief, title is in the assignee identified above.

The undersigned is empowered to sign this certificate on behalf of the assignee.

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made on information and belief are believed to be true; and further, that these statements are made with the knowledge that willful false statements, and the like so made, are punishable by fine or imprisonment, or both, under Section 1001, Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.